

PMP10218_RevB Board

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	0.15uF	B32922C3154M	TDK	CAP, Film, 0.15 μ F, 630 V, +/- 20%, TH	B32922_12mm
C2	1	4.7uF	EKMG401ELL4R7MJ16S	Used in BOM report	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output and some BOM reports
C3	1	1uF	EKMG401ELL1R0MF11D	Used in BOM report	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output and some BOM reports
C4	1	10uF	C2012X7R1A106M125AC	TDK	CAP, CERM, 10 μ F, 10 V, +/- 20%, X7R, 0805	0805
C5	1	DNP	Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	1206
C6	1	100uF	EEE-FC1A101P	Panasonic	CAP, AL, 100 μ F, 10 V, +/- 20%, 0.4 ohm, SMD	SMT Radial E
C7	1	1uF	C2012X7R1H105K125AB	TDK	CAP, CERM, 1 μ F, 50 V, +/- 10%, X7R, 0805	0805
C8	1	0.1uF	C2012X7R1H104K	TDK	CAP, CERM, 0.1 μ F, 50 V, +/- 10%, X7R, 0805	0805
C9	1	DNP	DNP	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603
C10	1	22pF	06035A220JAT2A	AVX	CAP, CERM, 22 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
C11	1	3300pF	DE1E3KX332MN4AP01F	MuRata	CAP, CERM, 3300 pF, 300 V, +/- 20%, E, D10xT7mm	D10xT7mm
D1, D3	2	DNP	DNP	Littelfuse	Diode, TVS, Uni, 100 V, 400 W, SMA, Diode, Ultrafast, 600 V, 1 A, SMA	SMA
D2	1	400V	RH04-T	Diodes Inc.	Diode, Switching-Bridge, 600 V, 0.5 A, MiniDIP	MiniDIP
D4	1	40V	MBRA140T3G	ON Semiconductor	Diode, Schottky, 40 V, 1 A, SMA	SMA
D5	1	400V	US1G-13-F	Diodes Inc.	Diode, Ultrafast, 400 V, 1 A, SMA	SMA
D6	1	DNP	MMSZ5257B-7-F	Diodes Inc.	Diode, Zener, 33 V, 500 mW, SOD-123	SOD-123
F1	1		37202000001	Littelfuse	Fuse, 0.2 A, 250 V, TH	TR5 fuse 8.5mm DIA
L1, L2	2	1.5mH	7447462152	Würth Elektronik	Inductor, Unshielded Drum Core, Ferrite, 1.5 mH, 0.19 A, 6.54 ohm, TH	D6 x 8.5mm
Q1	1	400 V	STN2580	STMicroelectronics	Transistor, NPN, 400 V, 1 A, SOT-223	SOT-223
R1, R3, R6	3	2.00Meg	CRCW08052M00FKEA	Vishay-Dale	RES, 2.00 M, 1%, 0.125 W, 0805	0805
R2, R5	2	DNP	CRCW080510K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.125 W, 0805	0805
R4	1	DNP	DNP	Vishay-Dale	RES, 100, 1%, 0.25 W, 1206	1206
R7	1	4.99k	CRCW08054K99FKEA	Vishay-Dale	RES, 4.99 k, 1%, 0.125 W, 0805	0805
R8	1	10.0	RC0805FR-0710RL	Yageo America	RES, 10.0, 1%, 0.125 W, 0805	0805
R9	1	237k	CRCW0603237KFKEA	Vishay-Dale	RES, 237 k, 1%, 0.1 W, 0603	0603
R10	1	0	CRCW08050000Z0EA	Vishay-Dale	RES, 0, 5%, 0.125 W, 0805	0805
R11	1	10.0k	CRCW080510K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.125 W, 0805	0805
R12	1	2.37k	CRCW06032K37FKEA	Vishay-Dale	RES, 2.37 k, 1%, 0.1 W, 0603	0603
R13	1	DNP	Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	0603
R14	1	43.2k	RC0603FR-0743K2L	Yageo America	RES, 43.2 k, 1%, 0.1 W, 0603	0603
R15	1	8.45	CRCW08058R45FKEA	Vishay-Dale	RES, 8.45, 1%, 0.125 W, 0805	0805
RF1	1	SHORT	SPP1UL1000JLF	TT Electronics/IRC	RES, 100, 5%, 1 W, TH	TH, 2-Leads, Axial, Dia 3.8mm, Pin Spacing 15.2mm
RV1	1	DNP	S10K275E2	EPCOS Inc	Varistor 275V RMS 10MM Radial, TH	10mm Radial
T1	1	4mH	750315727	Würth Elektronik	Transformer, 4 mH, TH	20.45x13.72mm
TP1, TP2, TP3	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP4	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
U1	1		UCC28722DBVR	Texas Instruments	Constant-Voltage, Constant-Current Controller With Primary-Side Regulation, BJT Drive, DBV0006A	DBV0006A

DNP = DO NOT POPULATE

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